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Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	5000
Number of I/O	164
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7256aeqc208-10

MAX 7000A devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000A architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000A devices contain from 32 to 512 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms, providing up to 32 product terms per macrocell.

MAX 7000A devices provide programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000A devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000A devices can be set for 2.5 V or 3.3 V, and all input pins are 2.5-V, 3.3-V, and 5.0-V tolerant, allowing MAX 7000A devices to be used in mixed-voltage systems.

MAX 7000A devices are supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2.0.0 and 3.0.0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

Parallel Expanders

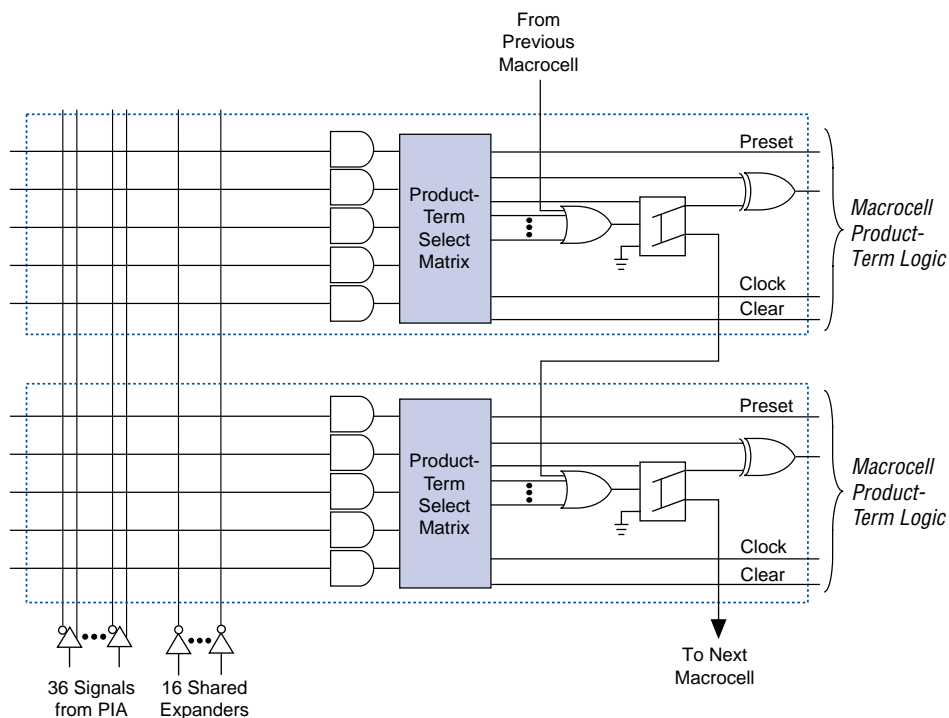
Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with five product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

The compiler can allocate up to three sets of up to five parallel expanders to the macrocells that require additional product terms. Each set of five parallel expanders incurs a small, incremental timing delay (t_{PEXP}). For example, if a macrocell requires 14 product terms, the compiler uses the five dedicated product terms within the macrocell and allocates two sets of parallel expanders; the first set includes five product terms, and the second set includes four product terms, increasing the total delay by $2 \times t_{PEXP}$.

Two groups of eight macrocells within each LAB (e.g., macrocells 1 through 8 and 9 through 16) form two chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of eight, the lowest-numbered macrocell can only lend parallel expanders, and the highest-numbered macrocell can only borrow them. [Figure 4](#) shows how parallel expanders can be borrowed from a neighboring macrocell.

Figure 4. MAX 7000A Parallel Expanders

Unused product terms in a macrocell can be allocated to a neighboring macrocell.



Programmable Interconnect Array

Logic is routed between LABs on the PIA. This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000A dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 5 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000A Device

The time required to program a single MAX 7000A device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where:

t_{PROG}	= Programming time
t_{PPULSE}	= Sum of the fixed times to erase, program, and verify the EEPROM cells
$Cycle_{PTCK}$	= Number of TCK cycles to program a device
f_{TCK}	= TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000A device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where:

t_{VER}	= Verify time
t_{VPULSE}	= Sum of the fixed times to verify the EEPROM cells
$Cycle_{VTCK}$	= Number of TCK cycles to verify a device

Table 8. MAX 7000A JTAG Instructions

JTAG Instruction	Description
SAMPLE/PRELOAD	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins
EXTEST	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins
BYPASS	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation
IDCODE	Selects the IDCODE register and places it between the TDI and TDO pins, allowing the IDCODE to be serially shifted out of TDO
USERCODE	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE value to be shifted out of TDO. The USERCODE instruction is available for MAX 7000AE devices only
UESCODE	These instructions select the user electronic signature (UESCODE) and allow the UESCODE to be shifted out of TDO. UESCODE instructions are available for EPM7128A and EPM7256A devices only.
ISP Instructions	These instructions are used when programming MAX 7000A devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, or BitBlaster download cable, or using a Jam STAPL File, JBC File, or SVF File via an embedded processor or test equipment.

Power Sequencing & Hot-Socketing

Because MAX 7000A devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. The V_{CCIO} and V_{CCINT} power planes can be powered in any order.

Signals can be driven into MAX 7000AE devices before and during power-up (and power-down) without damaging the device. Additionally, MAX 7000AE devices do not drive out during power-up. Once operating conditions are reached, MAX 7000AE devices operate as specified by the user.

MAX 7000AE device I/O pins will not source or sink more than 300 μ A of DC current during power-up. All pins can be driven up to 5.75 V during hot-socketing, except the OE1 and GLCRn pins. The OE1 and GLCRn pins can be driven up to 3.6 V during hot-socketing. After V_{CCINT} and V_{CCIO} reach the recommended operating conditions, these two pins are 5.0-V tolerant.

EPM7128A and EPM7256A devices do not support hot-socketing and may drive out during power-up.

Design Security

All MAX 7000A devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

Generic Testing

MAX 7000A devices are fully tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in [Figure 9](#). Test patterns can be used and then erased during early stages of the production flow.

Table 14. MAX 7000A Device Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CCINT}	Supply voltage for internal logic and input buffers	(3), (13)	3.0	3.6	V
V _{CCIO}	Supply voltage for output drivers, 3.3-V operation	(3)	3.0	3.6	V
	Supply voltage for output drivers, 2.5-V operation	(3)	2.3	2.7	V
V _{CCISP}	Supply voltage during in-system programming		3.0	3.6	V
V _I	Input voltage	(4)	−0.5	5.75	V
V _O	Output voltage		0	V _{CCIO}	V
T _A	Ambient temperature	Commercial range	0	70	°C
		Industrial range (5)	−40	85	°C
T _J	Junction temperature	Commercial range	0	90	°C
		Industrial range (5)	−40	105	°C
		Extended range (5)	−40	130	°C
t _R	Input rise time			40	ns
t _F	Input fall time			40	ns

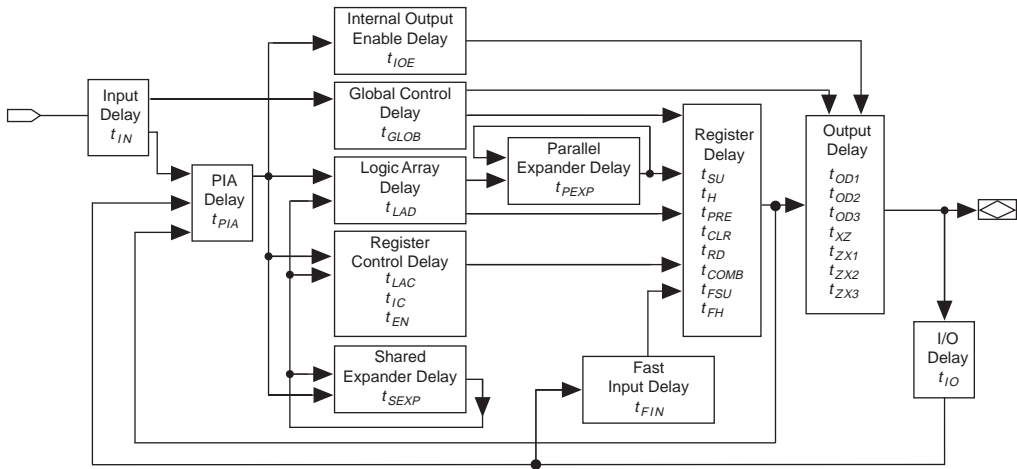
Table 15. MAX 7000A Device DC Operating Conditions *Note (6)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{IH}	High-level input voltage		1.7	5.75	V
V_{IL}	Low-level input voltage		-0.5	0.8	V
V_{OH}	3.3-V high-level TTL output voltage	$I_{OH} = -8$ mA DC, $V_{CCIO} = 3.00$ V (7)	2.4		V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1$ mA DC, $V_{CCIO} = 3.00$ V (7)	$V_{CCIO} - 0.2$		V
	2.5-V high-level output voltage	$I_{OH} = -100$ μ A DC, $V_{CCIO} = 2.30$ V (7)	2.1		V
		$I_{OH} = -1$ mA DC, $V_{CCIO} = 2.30$ V (7)	2.0		V
		$I_{OH} = -2$ mA DC, $V_{CCIO} = 2.30$ V (7)	1.7		V
V_{OL}	3.3-V low-level TTL output voltage	$I_{OL} = 8$ mA DC, $V_{CCIO} = 3.00$ V (8)		0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1$ mA DC, $V_{CCIO} = 3.00$ V (8)		0.2	V
	2.5-V low-level output voltage	$I_{OL} = 100$ μ A DC, $V_{CCIO} = 2.30$ V (8)		0.2	V
		$I_{OL} = 1$ mA DC, $V_{CCIO} = 2.30$ V (8)		0.4	V
		$I_{OL} = 2$ mA DC, $V_{CCIO} = 2.30$ V (8)		0.7	V
I_I	Input leakage current	$V_I = -0.5$ to 5.5 V (9)	-10	10	μ A
I_{OZ}	Tri-state output off-state current	$V_I = -0.5$ to 5.5 V (9)	-10	10	μ A
R_{ISP}	Value of I/O pin pull-up resistor during in-system programming or during power-up	$V_{CCIO} = 3.0$ to 3.6 V (10)	20	50	k Ω
		$V_{CCIO} = 2.3$ to 2.7 V (10)	30	80	k Ω
		$V_{CCIO} = 2.3$ to 3.6 V (11)	20	74	k Ω

Table 16. MAX 7000A Device Capacitance *Note (12)*

Symbol	Parameter	Conditions	Min	Max	Unit
C_{IN}	Input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		8	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		8	pF

Figure 11. MAX 7000A Timing Model



The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 12 shows the timing relationship between internal and external delay parameters.



See [Application Note 94 \(Understanding MAX 7000 Timing\)](#) for more information.

Tables 17 through 30 show EPM7032AE, EPM7064AE, EPM7128AE, EPM7256AE, EPM7512AE, EPM7128A, and EPM7256A timing information.

Table 17. EPM7032AE External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		4.5		7.5		10	ns
t _{SU}	Global clock setup time	(2)	2.9		4.7		6.3		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.0	1.0	5.0	1.0	6.7	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.6		2.5		3.6		ns
t _{AH}	Array clock hold time	(2)	0.3		0.5		0.5		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.3	1.0	7.2	1.0	9.4	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		4.4		7.2		9.7	ns
f _{CNT}	Maximum internal global clock frequency	(2), (4)	227.3		138.9		103.1		MHz
t _{ACNT}	Minimum array clock period	(2)		4.4		7.2		9.7	ns
f _{ACNT}	Maximum internal array clock frequency	(2), (4)	227.3		138.9		103.1		MHz

Table 18. EPM7032AE Internal Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-4		-7		-10		
			Min	Max	Min	Max	Min	Max	
t_{IC}	Array clock delay			1.2		2.0		2.5	ns
t_{EN}	Register enable time			0.6		1.0		1.2	ns
t_{GLOB}	Global control delay			0.8		1.3		1.9	ns
t_{PRE}	Register preset time			1.2		1.9		2.6	ns
t_{CLR}	Register clear time			1.2		1.9		2.6	ns
t_{PIA}	PIA delay	(2)		0.9		1.5		2.1	ns
t_{LPA}	Low-power adder	(6)		2.5		4.0		5.0	ns

Table 21. EPM7128AE External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t _{SU}	Global clock setup time	(2)	3.3		4.9		6.6		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.4	1.0	5.0	1.0	6.6	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.8		2.8		3.8		ns
t _{AH}	Array clock hold time	(2)	0.2		0.3		0.4		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.9	1.0	7.1	1.0	9.4	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		5.2		7.7		10.2	ns
f _{CNT}	Maximum internal global clock frequency	(2), (4)	192.3		129.9		98.0		MHz
t _{ACNT}	Minimum array clock period	(2)		5.2		7.7		10.2	ns
f _{ACNT}	Maximum internal array clock frequency	(2), (4)	192.3		129.9		98.0		MHz

Table 22. EPM7128AE Internal Timing Parameters (Part 1 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.7		1.0		1.4	ns
t_{IO}	I/O input pad and buffer delay			0.7		1.0		1.4	ns
t_{FIN}	Fast input delay			2.5		3.0		3.4	ns
t_{SEXP}	Shared expander delay			2.0		2.9		3.8	ns
t_{PEXP}	Parallel expander delay			0.4		0.7		0.9	ns
t_{LAD}	Logic array delay			1.6		2.4		3.1	ns
t_{LAC}	Logic control array delay			0.7		1.0		1.3	ns
t_{IOE}	Internal output enable delay			0.0		0.0		0.0	ns
t_{OD1}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		0.8		1.2		1.6	ns
t_{OD2}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 2.5\text{ V}$	$C1 = 35\text{ pF}$ (5)		1.3		1.7		2.1	ns
t_{OD3}	Output buffer and pad delay, slow slew rate = on $V_{CCIO} = 2.5\text{ V}$ or 3.3 V	$C1 = 35\text{ pF}$		5.8		6.2		6.6	ns
t_{ZX1}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		4.0		4.0		5.0	ns
t_{ZX2}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 2.5\text{ V}$	$C1 = 35\text{ pF}$ (5)		4.5		4.5		5.5	ns
t_{ZX3}	Output buffer enable delay, slow slew rate = on $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	$C1 = 5\text{ pF}$		4.0		4.0		5.0	ns
t_{SU}	Register setup time		1.4		2.1		2.9		ns
t_H	Register hold time		0.6		1.0		1.3		ns
t_{FSU}	Register setup time of fast input		1.1		1.6		1.6		ns
t_{FH}	Register hold time of fast input		1.4		1.4		1.4		ns
t_{RD}	Register delay			0.8		1.2		1.6	ns
t_{COMB}	Combinatorial delay			0.5		0.9		1.3	ns
t_{IC}	Array clock delay			1.2		1.7		2.2	ns

Table 22. EPM7128AE Internal Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t_{EN}	Register enable time			0.7		1.0		1.3	ns
t_{GLOB}	Global control delay			1.1		1.6		2.0	ns
t_{PRE}	Register preset time			1.4		2.0		2.7	ns
t_{CLR}	Register clear time			1.4		2.0		2.7	ns
t_{PIA}	PIA delay	(2)		1.4		2.0		2.6	ns
t_{LPA}	Low-power adder	(6)		4.0		4.0		5.0	ns

Table 23. EPM7256AE External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF (2)		5.5		7.5		10	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF (2)		5.5		7.5		10	ns
t _{SU}	Global clock setup time	(2)	3.9		5.2		6.9		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.5	1.0	4.8	1.0	6.4	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	2.0		2.7		3.6		ns
t _{AH}	Array clock hold time	(2)	0.2		0.3		0.5		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	5.4	1.0	7.3	1.0	9.7	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		5.8		7.9		10.5	ns
f _{CNT}	Maximum internal global clock frequency	(2), (4)	172.4		126.6		95.2		MHz
t _{ACNT}	Minimum array clock period	(2)		5.8		7.9		10.5	ns
f _{ACNT}	Maximum internal array clock frequency	(2), (4)	172.4		126.6		95.2		MHz

Table 28. EPM7128A Internal Timing Parameters (Part 2 of 2) *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-12		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{RD}	Register delay			1.7		2.1		2.8		3.3	ns
t_{COMB}	Combinatorial delay			1.7		2.1		2.8		3.3	ns
t_{IC}	Array clock delay			2.4		3.0		4.1		4.9	ns
t_{EN}	Register enable time			2.4		3.0		4.1		4.9	ns
t_{GLOB}	Global control delay			1.0		1.2		1.7		2.0	ns
t_{PRE}	Register preset time			3.1		3.9		5.2		6.2	ns
t_{CLR}	Register clear time			3.1		3.9		5.2		6.2	ns
t_{PIA}	PIA delay	(2)		0.9		1.1		1.5		1.8	ns
t_{LPA}	Low-power adder	(6)		11.0		10.0		10.0		10.0	ns

The parameters in this equation are:

- MC_{TON} = Number of macrocells with the Turbo Bit option turned on, as reported in the MAX+PLUS II Report File (.rpt)
 MC_{DEV} = Number of macrocells in the device
 MC_{USED} = Total number of macrocells in the design, as reported in the Report File
 f_{MAX} = Highest clock frequency to the device
 to_{gLC} = Average percentage of logic cells toggling at each clock (typically 12.5%)
A, B, C = Constants, shown in [Table 31](#)

Table 31. MAX 7000A I_{CC} Equation Constants

Device	A	B	C
EPM7032AE	0.71	0.30	0.014
EPM7064AE	0.71	0.30	0.014
EPM7128A	0.71	0.30	0.014
EPM7128AE	0.71	0.30	0.014
EPM7256A	0.71	0.30	0.014
EPM7256AE	0.71	0.30	0.014
EPM7512AE	0.71	0.30	0.014

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

Figure 15. 49-Pin Ultra FineLine BGA Package Pin-Out Diagram

Package outlines not drawn to scale.



Figure 16. 84-Pin PLCC Package Pin-Out Diagram

Package outline not drawn to scale.

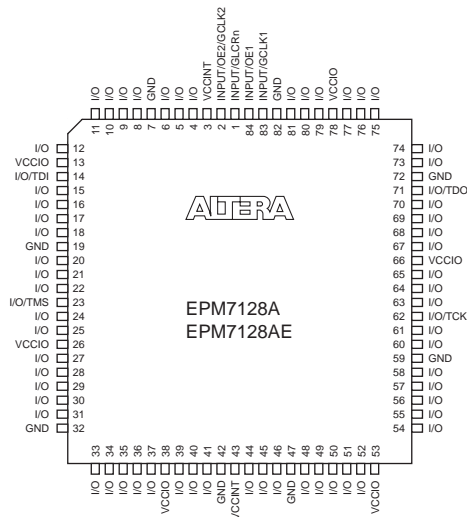


Figure 19. 144-Pin TQFP Package Pin-Out Diagram

Package outline not drawn to scale.

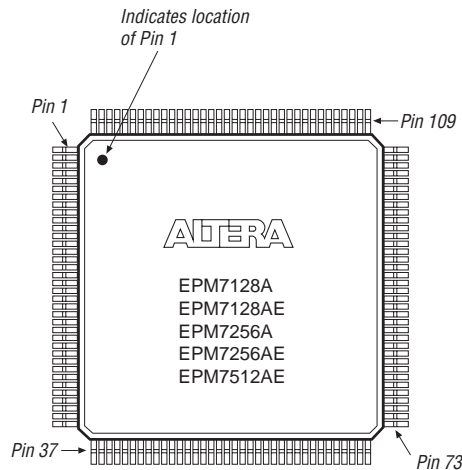
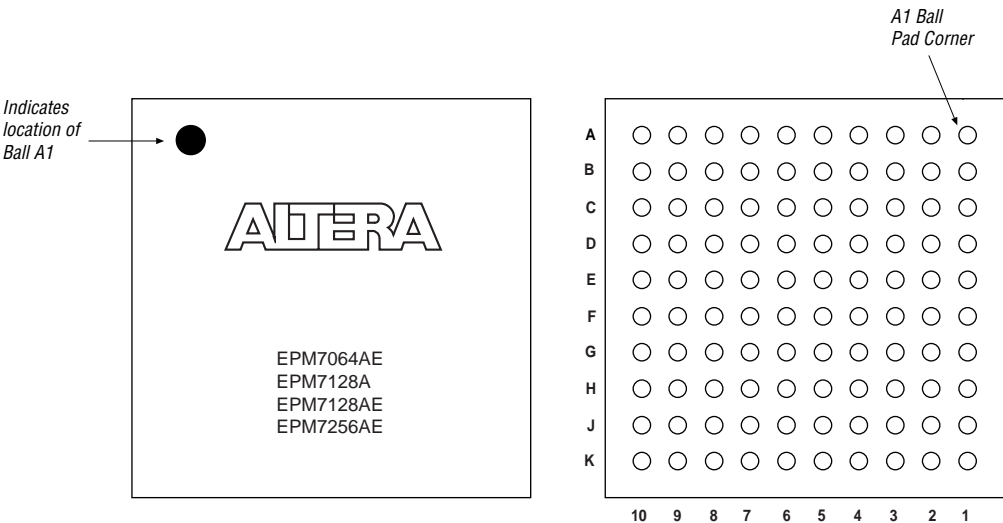


Figure 20. 169-Pin Ultra FineLine BGA Package Pin-Out Diagram

Package outline not drawn to scale.



Version 4.3

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.3:

- Added extended temperature devices to document
- Updated [Table 14](#).

Version 4.2

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.2:

- Removed *Note (1)* from [Table 2](#).
- Removed *Note (4)* from [Tables 3](#) and [4](#).

Version 4.1

The following changes were made in the *MAX 7000A Programmable Logic Device Data Sheet* version 4.1:

- Updated leakage current information in [Table 15](#).
- Updated [Note \(9\)](#) of [Table 15](#).
- Updated [Note \(1\)](#) of [Tables 17](#) through [30](#).



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